



P R E S S R E L E A S E

X-FAB Qualifies Agilent Technologies' GoldenGate and Momentum Simulators for its 0.35 Micrometer CMOS Process Family

Erfurt, Germany – June 4, 2012 – X-FAB Silicon Foundries, a leading foundry group for analog/mixed-signal semiconductor applications, today announced support for Agilent Technologies' GoldenGate RFIC circuit and Momentum 3D planar electromagnetic (EM) simulators for X-FAB's 0.35 micrometer modular analog mixed-signal technology with RF capability and high-voltage extensions.

“Adding RF content to advanced mixed-signal SoC presents significant challenges,” said Thomas Ramsch, Director Design Support at X-FAB. “Support for GoldenGate and Momentum provides our customers with access to Agilent's proven expertise in RF and microwave design. Our customers welcome any opportunity to streamline the development process, so we are pleased to qualify and endorse Agilent's RFIC solutions for our process technologies.”

Agilent's GoldenGate RFIC simulation and analysis software is the most trusted simulation, verification and analysis solution available today for integrated RF circuit design. Its unique simulation algorithms enable full characterization of complete transceivers prior to tape-out. Momentum is a powerful 3D planar EM simulator for RF passive component design and analysis of high-frequency effects related to on-chip interconnects and other layout structures. Both, GoldenGate and Momentum are seamlessly integrated into the Cadence® Virtuoso® Platform.

“Having collaborated with X-FAB for quite some time, I'm very pleased that we have reached yet another milestone,” said Juergen Hartung, foundry program manager of Agilent EEs of EDA.

“With the qualification of GoldenGate and Momentum, our customers can now enjoy the industry's most comprehensive RFIC simulation and EM and analysis support within X-FAB's modular analog mixed-signal technology to increase their performance, consistency and yield.”

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About X-FAB

X-FAB is the leading analog/mixed-signal foundry group manufacturing silicon wafers for analog-digital integrated circuits (mixed-signal ICs). X-FAB maintains wafer production facilities in Erfurt and Dresden (Germany); Lubbock, Texas (U.S.); and Kuching, Sarawak (Malaysia); and employs approximately 2,400 people worldwide. Wafers are manufactured based on advanced modular CMOS and BiCMOS processes with technologies ranging from 1.0 to 0.13 micrometers, for applications primarily in the automotive, communications, consumer and industrial sectors. For more information, please visit www.xfab.com.

X-FAB Press Contacts

Thomas Hartung
VP Marketing
+49-361-427-6160
thomas.hartung@xfab.com

X-FAB Semiconductor Foundries AG
Haarbergstr. 67
99097 Erfurt, Germany
www.xfab.com

ThinkBold Corporate Communications
Dagmar Berendes
+1-408-379-2344
dagmar@thinkbold.com

Sarah Miller
+1-231-264-8636
sarah@thinkbold.com